



**标准&定制开关连接器产品制造商**  
DONG GUAN XI BANG ELECTRONICS CO., LTD.

# 规格书

## SPECIFICATION

CUSTOMER NAME 客户名称: \_\_\_\_\_  
 CUSTOMER NO. 客户编号: \_\_\_\_\_  
 SERIES 系列: **耳机插座**  
 MODEL NO. 型号: \_\_\_\_\_  
 DRAWING NO. 图形号: **Audio Jack**

If specification of this product meets your request, please confirm all the items of it and return to us with signature and stamp, it will be basis of our production and record. Thanks your cooperation in advance!

若此产品规格符合贵司要求，敬请确认此规格书内所有项目  
 并签名和盖章后回传给我司，以作我司产品制作之  
 依据和存档之用，多谢合作！

### EXAMINE & APPROVAL 审批

APPROVE 接受	NOT APPROVE 不接受
SIGNATURE 签署      STAMP 盖章      DATE 日期	

PREPARED BY. 制表人	CHECKED BY. 校对	APPROVED BY. 审核	APPROVAL BY. 批准
研发部 戴海明 2022. 06. 08	品质部 黄自清 2022. 06. 08	工程部 庞军 2022. 06. 08	总经办 吴量 2022. 06. 08

**东莞市溪榜电子有限公司**

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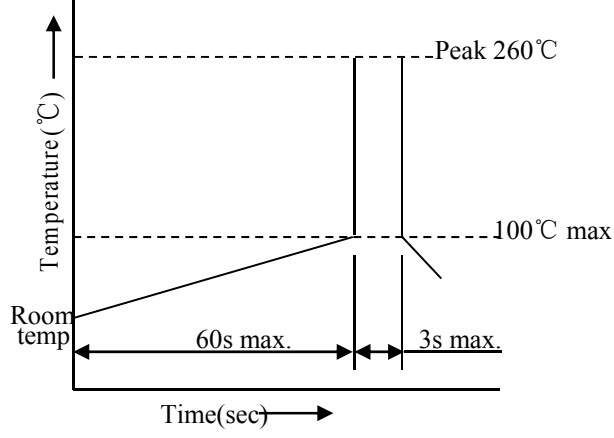
邮箱: admin@alspr.com    switch@alspr.com  
<http://www.alspr.cn/>    <http://www.alspr.com/>

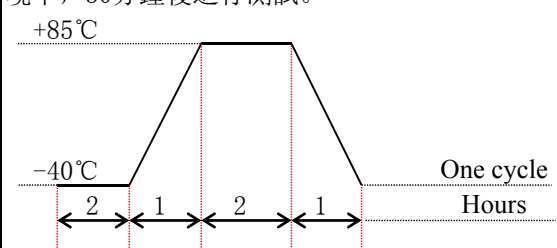
**Dong Guan XB Electronics Co., Ltd**

Account Number : 705540238  
 Bank Name : Citi bank N. A. , Hong Kong Branch  
 Country/Region: Hong Kong  
 Bank Code: 006  
 Bank Address : 3 Garden Road, Central, Hong Kong  
 SWIFT/BIC : CITIHKHX (CITIHKHXXXX\* If 11 characters are required)

MAil : HK@ALPSR.CN    XB@ALPSR.CN  
 Quality core! Afterburner for Made in China!



ITEM 項目	TEST CONDITION 測試條件	PERFORMAENCE 性能		
<b>8. DURABILITY 耐久性</b>				
8.1	SOLDERING TEST 可焊性試驗	<p>The tip of the terminals shall be dipped 2 mm in the solder bath within temperature of 250±5°C for 3 seconds. 端子頂部被浸入焊錫池 2mm 深, 溫度250±5°C, 時間3秒。</p>	<p>Over 95% of the immersed surface was covered by tin. 浸入的部份95%以上表面將被錫覆蓋。</p>	
		<p>The condition mentioned is temperature for lead-free soldering . 無鉛錫測試 Alloy: Sn 96.5% Cu 3% Ag 0.5% 成份: 錫 96.5% 銅 3% 銀 0.5%</p>		
8.2	SOLDERING RESISTANT TEST 耐焊性試驗	<p>Manual soldering temperature 300±5°C, soldering time 3±0.5 seconds, however excessive pressure shall not be applied to the terminal. 手焊接的時候溫度需控制在300±5°C, 時間為3±0.5秒, 但不能在端子上施加異常壓力。</p>	<p>Without deformation of case or excessive looseness of teminals, meet mechanical and electrical properties 本體無變形, 能滿足於機械、電器性能。</p>	
		<p>The condition mentioned is temperature for lead-free soldering . 無鉛錫測試。 Alloy: Sn 96.5% Cu 3% Ag 0.5% 成份: 錫 96.5% 銅 3% 銀 0.5%</p>		
8.3	Wave soldering 波峰焊	<p>When applying wave soldering, the peak temperature of the wave Oven should be set to 260°C max. 當使用低波爐進行焊接時, 最高溫度設置為260°C. ondition for soldering (Wave &amp; Non-washable Type) Temperature Profile: 焊接溫度曲線圖如下:</p> 	<p>There shall be no defects in appearance or in the mechanical functions. 沒有出現任何外觀和機械功能上的損傷。</p>	
		Items	Condition	
		Preheating temperature	Ambient temperature of the soldered surface of PC board 100°C max.	
		Preheating time	60s max.	
		Soldering temperature	260°C max.	
		Continuous dipping time	3s max.	
		Number of soldering	1 times max.	

ITEM 項目		TEST CONDITION 測試條件	PERFORMAENCE 性能
8.4	LIFE TEST 壽命試驗	5000 cycles of operation at a rate of 15-18 cycles per minute with unloading 無負載條件下，每分鐘 15~18 次的速度操作 5000 次。	(1) Contact resistance 150mΩ max. 接觸電阻150毫歐 以下 (2) Insertion force: 插入力度: 0.25~2.0kgf Extraction force: 拔出力度: 0.2~1.5kgf (3) ITEM 項目—6.2 (4) ITEM 項目—6.3
8.5	HEAT RESISTANT TEST 耐熱試驗	80±2°C for 96 hours, test after keeping in normal condition for 30 minutes. 在 80±2°C 環境中放96小時, 再放在正常環境中30分鐘後進行測試。	(1) Contact resistance 150 mΩ max. 接觸電阻150毫歐以下 (2) Insulation resistance 50 MΩ min. 絕緣電阻50兆歐以上 (3) ITEM 項目—6.2 (4) ITEM 項目—6.3
8.6	MOISTURE RESISTANT TEST 耐濕試驗	40±2°C 90-95% RH for 96 hours, test after keeping in normal condition for 30 minutes. 在40±2°C 90-95% RH 環境中放96小時, 再放在正常環境中, 30分鐘後進行測試。	(3) ITEM 項目—6.2 (4) ITEM 項目—6.3
8.7	COLD RESISTANT TEST 耐冷試驗	At -40±3°C for 96 hours, test after keeping in normal condition for 30minutes. 在 -40±3°C 環境中放96小時, 再置於正常環境中, 30分鐘後進行測試。	
8.8	TEMPERATURE CYCLING TEST 溫度交變試驗	According to following figure, after 5 cycles, test after keeping in normal condition for 30 minutes. 如圖示之環境中, 循環5次後, 再置於正常環境中, 30分鐘後進行測試。 	
8.9	STORAGE ENVIROMENT 儲存環境	Under sealing pack condition, stored temperature don't exceed 30°C and relative humidity is 75% RH; in the enviroment of no sunshine direct and no corrosive gas, the stored time ought to be three months but within six month at most. 密封包裝狀態下, 儲存溫度為≤30°C, 相對溫度 75% RH; 無陽光直射, 無腐蝕性氣體的環境中, 儲存時間為3個月, 最長不宜超過6個月。 Without sealing pack condition, stored temperature don't exceed 30°C and relative humidity is 75% RH; in the enviroment of no sunshine direct and no corrosive gas, the stored time shouldn't exceed 48H 無密封包裝狀態下, 儲存溫度為≤30°C, 相對溫度 75% RH; 無陽光直射, 無腐蝕性氣體的環境中, 儲存時間最長不宜超過48小時。 Don't excessive overlap or overstocking when keeping this goods, in case of damage. 保存時應注意物品不能過量重疊、積壓、以免損壞	